Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (2.4 x 1.65 EP)
Lead Count	8
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.01E-02	93.7	937000	48.43	484338
Thermosets	Epoxy Resin	Proprietary	3.22E-04	3.0	30000	1.55	15507
Thermosets	Phenol Resin	Proprietary	3.22E-04	3.0	30000	1.55	15507
Other inorganic materials	Carbon Black	1333-86-4	3.22E-05	0.3	3000	0.16	1551
Subtotal			1.07E-02	100.00	1000000	51.69	516902

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	9.09 E-03	97.50	975000	43.76	437596
Copper & its alloys	Iron	7439-89-6	2.19 E-04	2.35	23500	1.05	10547
Copper & its alloys	Zinc	7440-66-6	1.12 E-05	0.12	1200	0.05	539
Copper & its alloys	Phosphorus	7723-14-0	2.80 E-06	0.03	300	0.01	135
Subtotal			9.33 E-03	100.00	1000000	44.88	448816

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.42 E-05	100.0	1000000	0.45	4534

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.10 E-04	100.0	1000000	0.53	5294

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.90 E-05	99.00	990000	0.48	4765
Precious metals	Palladium	7440-05-3	1.00 E-06	1.0	10000	0.005	48
Subtotal			1.00 E-04	100.0	1000000	0.48	4813

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	3.78 E-04	100.0	1000000	1.82	18197

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.42 E-05	80.50	805000	0.12	1162
Other organic materials	Carbocyclic Acrylates	Proprietary	3.00 E-06	10.00	100000	0.01	144
Other organic materials	Bismaleimide resin	Proprietary	9.00 E-07	3.00	30000	0.004	43
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	9.00 E-07	3.0	30000	0.004	43
Others	Additive	Proprietary	9.00 E-07	3.0	30000	0.004	43
Other organic materials	Dicumyl peroxide	80-43-3	1.50 E-07	0.5	5000	0.001	7
Subtotal			3.00 E-05	100.0	1000000	0.14	1444

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.08 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES